Silicon P Channel Power MOS FET High Speed Power Switching

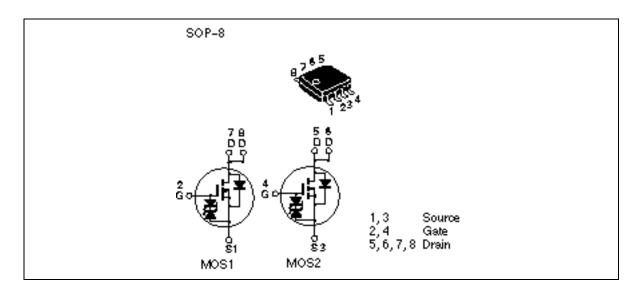
HITACHI

ADE-208-522 (Z) 1st. Edition May 1997

Features

- Low on-resistance
- Capable of 2.5 V gate drive
- Low drive current
- High density mounting

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	-20	V
Gate to source voltage	V_{GSS}	±10	V
Drain current	I_D	-3.5	A
Drain peak current	I _{D(pulse)} Note1	-28	A
Body-drain diode reverse drain current		-3.5	A
Channel dissipation	Pch Note2	2	W
Channel dissipation	Pch Note3	3	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: 1. PW \leq 10 μ s, duty cycle \leq 1 %

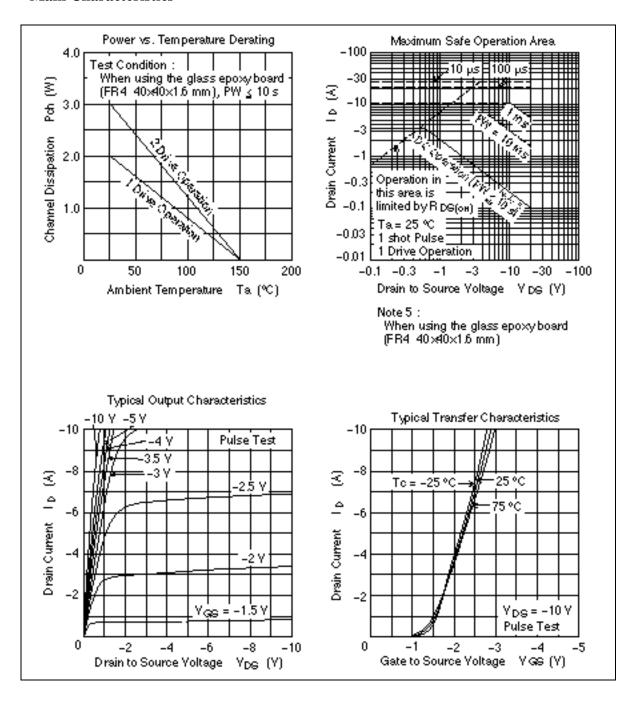
- 2. 1 Drive operation : When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW^2 10s
- 3. 2 Drive operation : When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), PW² 10s

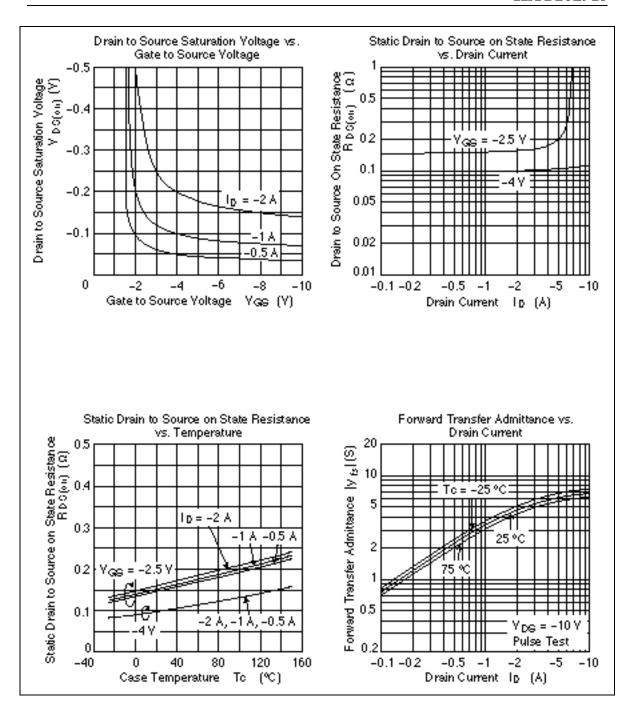
Electrical Characteristics ($Ta = 25^{\circ}C$)

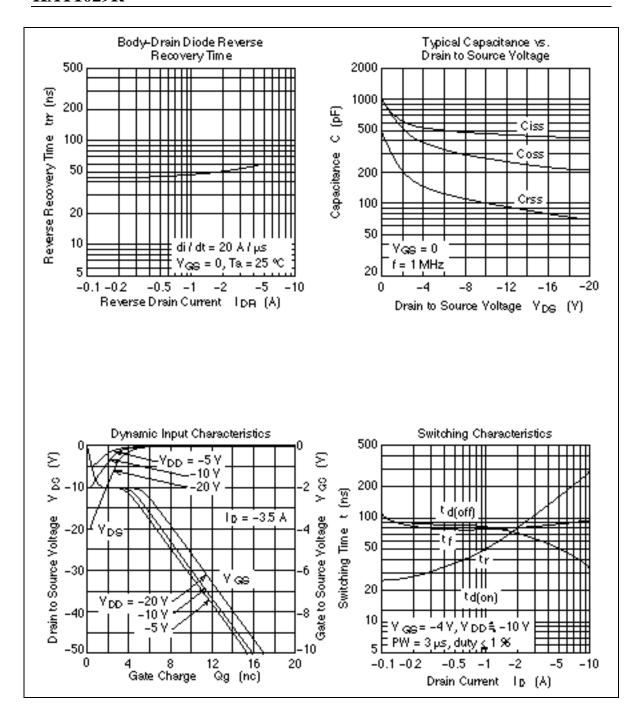
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR)DSS}	-20	_	_	V	$I_D = -10 \text{mA}, \ V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±10	_	_	V	$I_G = \pm 100 \mu A, V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 8V, V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}	_	_	–1	μΑ	$V_{DS} = -20 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-0.5	_	-1.5	V	$V_{DS} = -10V, I_D = -1mA$
Static drain to source on state	R _{DS(on)}	_	0.10	0.14	Ω	$I_D = -2A$, $V_{GS} = -4V^{Note4}$
resistance	R _{DS(on)}	_	0.16	0.23	Ω	I _D = -2A, V _{GS} = -2.5V Note4
Forward transfer admittance	y _{fs}	3	4.5	_	S	I _D = -2A, V _{DS} = -10V Note4
Input capacitance	Ciss	_	465	_	pF	V _{DS} = -10V
Output capacitance	Coss	_	270	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	100	_	pF	f = 1MHz
Turn-on delay time	t _{d(on)}	_	14	_	ns	$V_{GS} = -4V, I_D = -2A$
Rise time	t _r	_	80	_	ns	$V_{DD} \cong -10V$
Turn-off delay time	t _{d(off)}	_	70	_	ns	
Fall time	t _f	_	80	_	ns	
Body-drain diode forward voltage	V_{DF}	_	-0.95	-1.24	V	$IF = -3.5A$, $V_{GS} = 0^{Note4}$
Body-drain diode reverse recovery time	t _{rr}		55	_	ns	IF = $-3.5A$, $V_{GS} = 0$ diF/ dt =20A/ μ s
<u></u>						

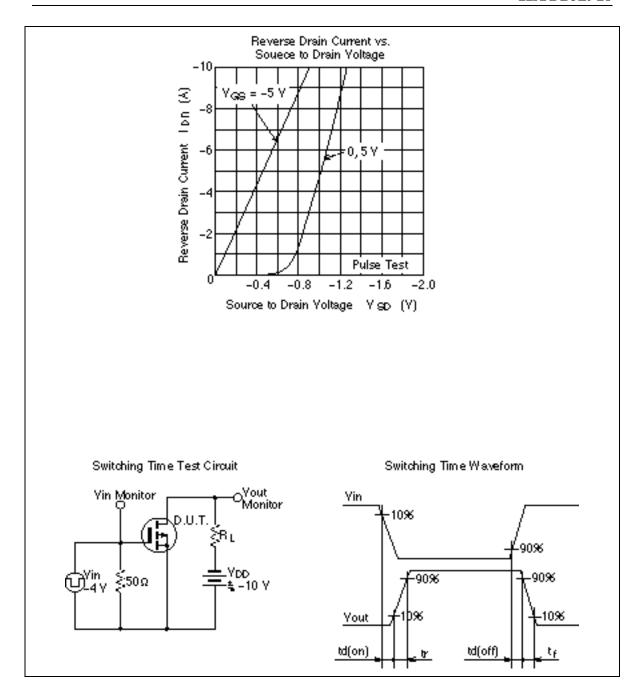
Note: 4. Pulse test

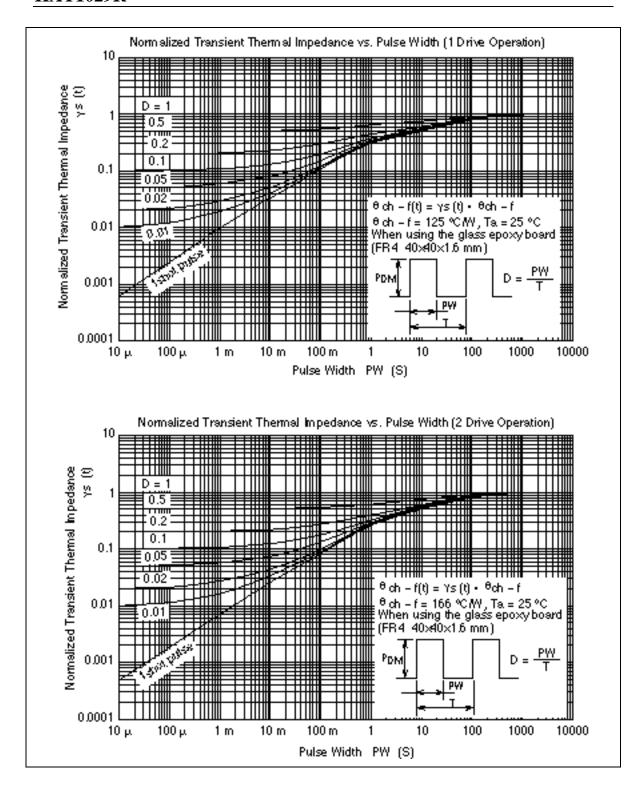
Main Characteristics





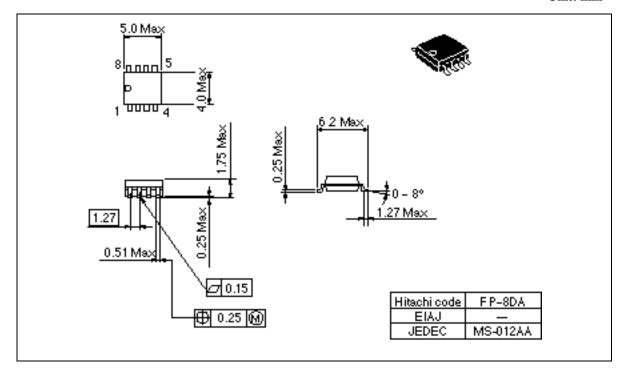






Package Dimensions

Unit: mm



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